

Overview

LB1908 is a dedicated chip for LED constant current drive with 3 channels of return to 0 code that supports resumable transmission. There are 3 open-drain constant current output terminals, support 256-level brightness adjustment, PWM refresh rate up to 8K, and provide output channel current misalignment processing methods that reduce electromagnetic interference and power supply clutter. The IC is directly connected to the 12V power supply to reduce the impact of voltage drop; the chip provides dual data inputs as redundant control to ensure signal transmission in the case of single chip damage. The chip provides SOP8 package.

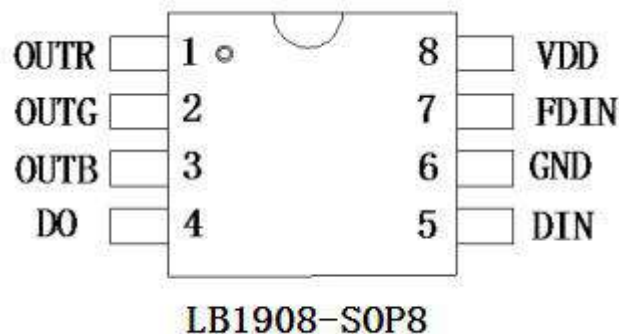
Applications

- LED Display
- LED lighting/light engineering

Features

- Using power CMOS technology, OUT output port withstand voltage 24V.
- Built-in 5V voltage regulator tube, working voltage 12V.
- Using return to 0 code, serial data transmission rate 800KHz.
- Fixed constant current output of 14mA, default does not turn on when power is on.
- PWM brightness control circuit, 256-level brightness adjustable; gray-scale clock supports 8KHZ refresh rate.
- Accurate current output value: (channel and channel) maximum error: $\pm 3\%$, (chip and chip) maximum error: $\pm 5\%$.
- Single-wire dual-channel serial cascading interface: switch between input interfaces in normal mode, DIN pin inputs data in DIN working mode, FDIN pin inputs data in FDIN working mode, DO forwards cascaded data, and the signal does not depend on a certain one. The chip is abnormal and affects the normal operation of other chips.
- Oscillation mode: Built-in RC oscillation and clock synchronization according to the signal on the data line, after receiving the data of this unit, the subsequent data can be automatically regenerated and sent to the lower level through the data output terminal, and the signal will not be distorted or distorted as the cascade becomes farther. Attenuation.
- Built-in power-on reset circuit, all registers are initialized to zero after power-on reset.
- ESD:HBM 3000V MM 300V
- Packaging:SOP8(4000PCS/Reel)

Pin Configuration



Pin Description

| PIN name | PIN NO. | I/O | Function |
|----------|---------|-----|--|
| DIN | 5 | I | Data input |
| FDIN | 7 | I | Backup data input |
| DO | 4 | O | Data output |
| GND | 6 | -- | Chip Ground |
| OUTR/G/B | 1、2、3 | O | Constant-current outputs, connected to LED |
| VDD | 8 | -- | 12V Power Supply |



Integrated circuit is an electrostatic sensitive device which tends to generate a lot of static electricity when used in a dry season or dry environment. Electrostatic discharge may damage integrated circuit. Titan Micro Electronics suggests taking all appropriate preventive measures for integrated circuit. Improper operation and welding might cause ESD damage or performance reduction and chip operation failure.

Maximum Ratings

| Parameter name | Parameter symbol | Limit value | Unit. |
|--------------------------|------------------------|--------------|-------|
| Power Source | VDD | -0.4~16 | V |
| On-chip Power Source | VCC | -0.4~6 | V |
| Input Logic Voltage | Vin | -0.4~VDD+0.5 | V |
| Output voltage-endurance | Vout | 26 | V |
| Maximum output current | <i>I_{out}</i> | 15 | mA |
| Working temperature | Topr | -40~+85 | °C |
| Storage temperature | Tstg | -50~+150 | °C |
| ESD | Human body model (HBM) | 3000 | V |
| | Machine model (MM) | 300 | V |

(1) When the chip works for a long time under the above limit parameters, it may cause device reliability reduction or permanent damage. We do not suggest the chip works by exceeding these limit parameters under any other conditions.

(2) All voltage values are comparatively tested in a systematic way.

Electrical characteristics

| Parameter name | Parameter symbol | Testing condition | Min | Typical | Max | Unit |
|----------------------------|--------------------|---|-----|---------|-----|------|
| Power supply | VDD | I _{oh} =3mA | 10 | 12 | 16 | V |
| High Input Logic Voltage | V _{ih} | VDD=5.0V | 4 | | VDD | V |
| Low Input Logic Voltage | V _{il} | VDD=5.0V | 0 | | 1.0 | V |
| Voltage range of outputs | V _{out} | OUT=OFF | | | 12 | V |
| Static current | I _{DD} | VDD=5.0V, GND=0V, 其他端口悬空 | 0.5 | 1.4 | 2.0 | mA |
| OUT output current | I _{out} | OUTR, OUTG, OUTB=ON, V _{out} =3.0V | 9 | 10 | 11 | mA |
| OUT output leakage current | I _{olk} | OUTR, OUTG, OUTB=OFF, V _{out} =12.0V | | | 0.5 | μA |
| Current variation(channel) | ΔI _{olc0} | OUTR, OUTG, OUTB=ON, V _{out} =3.0V | | | ±3 | % |

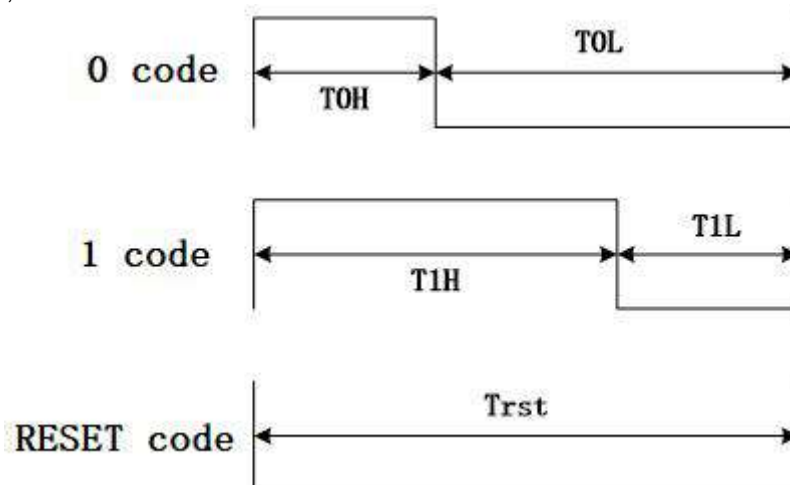
DC12V Power supply 3 channels LED driver

| | | | | | | |
|-------------------------|-------------------|---|--|-----|---------|---------|
| Current variation(chip) | ΔI_{olc1} | OUTR, OUTG, OUTB=ON, $V_{out}=3.0V$ | | | ± 5 | % |
| Power dissipation | P_d | $T_a=25^{\circ}C$ | | | 150 | mW |
| PWM refresh rate | F_{in} | | | 800 | | KHz |
| OUT PWM refresh rate | F_{out} | OUTR, OUTG, OUTB | | 8K | | Hz |
| Propagation delay time | T_{plz} | DIN \rightarrow DO FDIN \rightarrow DO | | 155 | 500 | ns |
| External Power Res | R_i | | | 50 | | ohm |
| External Power Cap | C_i | | | 0.1 | | μF |

Time sequence characteristics

| Parameter name | Parameter symbol | Testing condition | Min | Typical | Max | Unit | |
|-------------------------------|------------------|--------------------|-----|---------|-----|------|---------|
| Input 0 ode, high level time | T0H | VDD=5.0V GND=0V | 250 | 300 | 350 | ns | |
| Input 1 ode, high level time | T1H | | 700 | 800 | 900 | ns | |
| Output 0 ode, high level time | T0H' | | | | 300 | ns | |
| Output 1 ode, high level time | T1H' | | | | 800 | ns | |
| 0 code or 1 code cycle | T0/T1 | | | 1.1 | 1.2 | 1.3 | μs |
| Reset code, low level time | Treset | | | 200 | | | μs |

- (1) When 0 code or 1 code cycle is within the range of 1.2 μs (frequency 800KHz) , the chip can normally work, but the low level time of 0 code and 1 code must accord with the corresponding values in the above table;
- (2) When reset is not required, the low level time between bytes should not exceed 80 μs , or else the chip may be rest to receive data again, which cannot achieve correct data transmission.



Function description

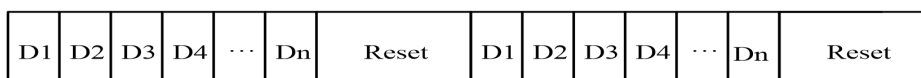
1. Display data

LB1908 adopts single-wire two-channel communication and adopts 0-code mode to send signals. After power-on reset and reception of a mode setting command, the chip begins to receive display data. When the 24-bit data are received, DO ports will start to forward the data continuously sent from DIN or FDIN port, which provides display data for the next cascaded chip. Prior to forwarding data, DO ports are always at low level. If DIN or FDIN port is input with Reset signals, chip OUT port will output the PWM waveform of corresponding duty ratio according to the received

24-bit data, and the chip will wait to receive new data again. Upon receiving the initial 24-bit data, DO port will forward the data. Before the chip receives no Reset signal, the original output of OUTR, OUTG and OUTB remains unchanged.

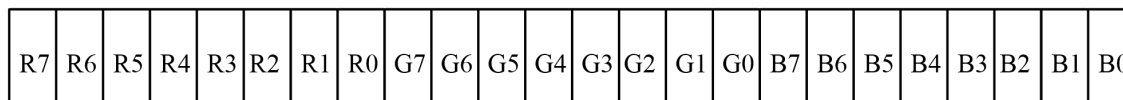
The chip adopts auto integer forwarding technology, so that the signals will not distort and attenuate. For all the cascaded chips, the cycles of data transmission are consistent.

2. Structure of a complete frame of data



The data formats of D1, D2, D3, D4, ... Dn are the same, wherein D1 means the display data packet of the first cascaded chip and Dn means the data display packet of the nth cascaded chip. Each display data packet contains 24 data bits. Reset means reset signal, valid at low level.

3. Data format of Dn



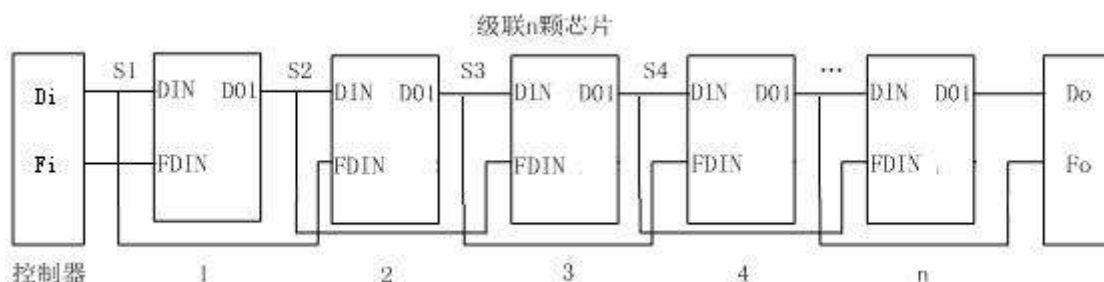
Each data packet contains 8×3 data bits, with higher bits sent first.

R[7:0]: used to set the PWM duty ratio output by OUTR. Full 0 code is off, full 1 code is of maximum duty ratio, 256-level adjustable.

G[7:0]: used to set the PWM duty ratio output by OUTG. Full 0 code is off, full 1 code is of maximum duty ratio, 256-level adjustable.

B[7:0]: used to set the PWM duty ratio output by OUTB. Full 0 code is off, full 1 code is of maximum duty ratio, 256-level adjustable.

4. Data reception and forwarding

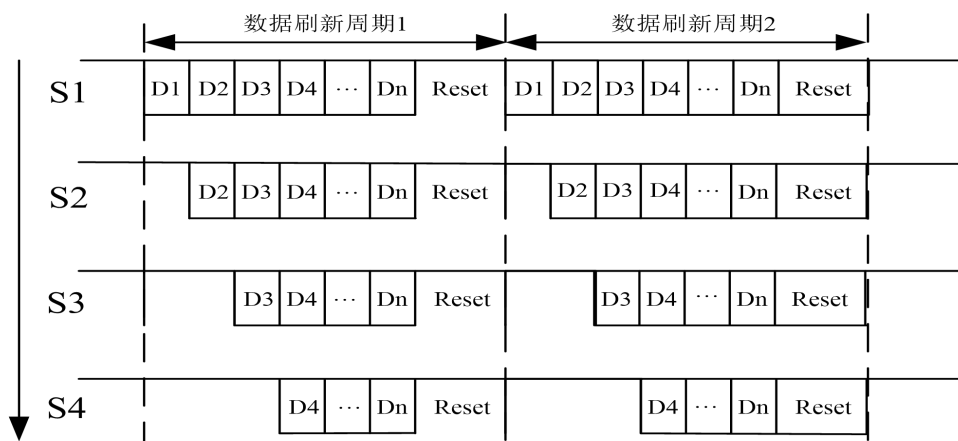


Special reminder: the IC PINS DIN and FDIN as two input of data is not the same, and exactly 24 bits of data, when FDIN received data, automatically lose the Dx that packet to achieve that data (display effect) will not shift, which is the first point to connect the controller using THE DIN port instead of the FDIN port.

Wherein, S1 is the data sent by Di port of the controller, S2, S3 and S4 are the data forwarded by cascaded LB1908.

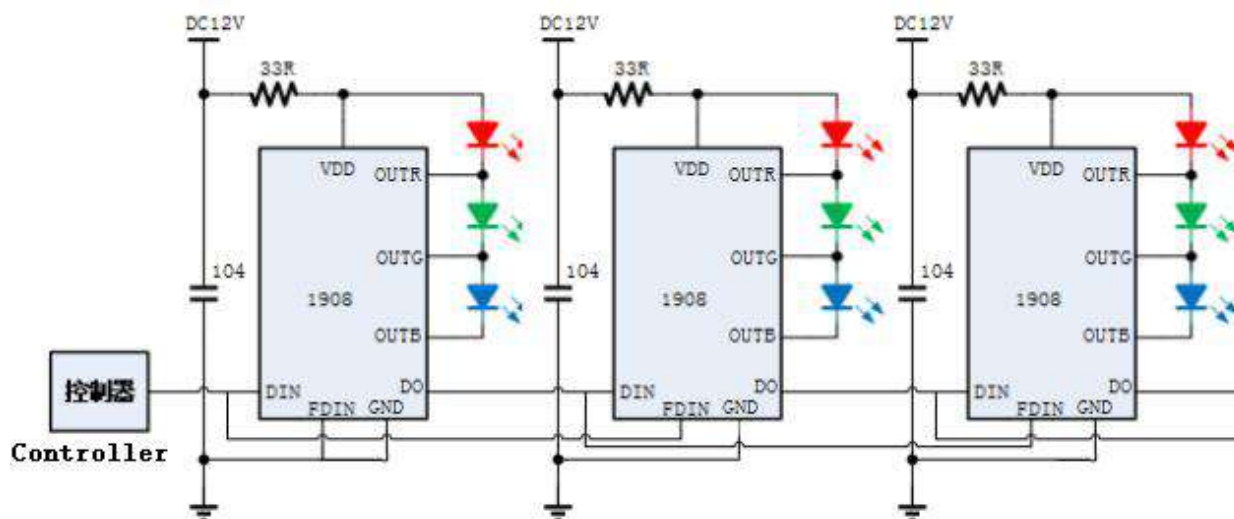
Data structure of Di and Fi2 ports of the controller: D1D2D3D4.....Dn;

Data structure of Fi port of the controller: Dx D1 D2 D3.....Dn; and the Dx is any 24bit data.



The data transmission and forwarding process when chips are cascaded is as follows: controller sends packet D1, Chip 1 receives the first set of 24bit, At this time, chip 1 has no forwarding; Then the controller sends the packet D2, Chip 1 receives the second set of 24 bits, Since the chip 1 already has the first set of 24 bits, Therefore, the chip 1 forwards the second group 24 bits to the chip 2 through the DO. The chip 2 receives the data packet D2 forwarded by the chip 1, At this time, chip 2 has no forwarding; The controller then sends the packet D3, Chip 1 forwards the received third set of 24 bits to chip 2, Since the chip 2 already has a second set of 24 bits, Therefore, the chip 2 forwards the third group 24bit to the chip 3, and the chip 3 receives the third group 24bit; and so forth, until the controller sends Reset signal, all the chips will reset and control the received 24-bit data to output them from OUT port after decoding, which completes a data refresh cycle and makes the chips return to the reception-ready state. Reset is valid at low level. To make the chip reset, the low level time should be maintained at more than 200 μ s.

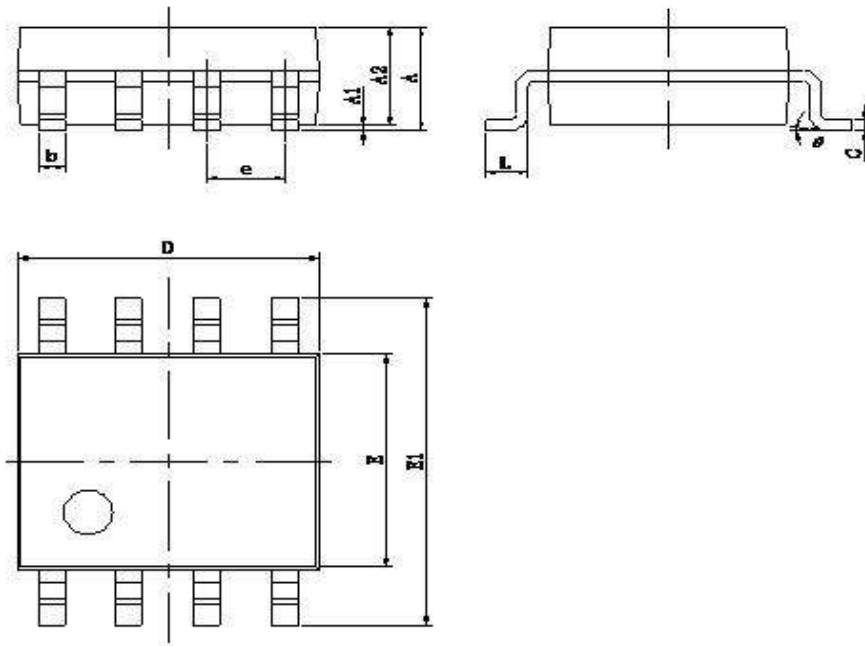
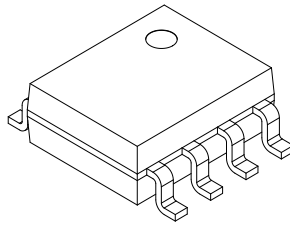
Typical application circuit



To prevent chip signal input/output pin damage caused by the transient peak voltage generated by hot plugging when the product is tested, 68-100 Ω protective resistors should be connected in parallel at signal input and output pins. Besides, the 104 decoupling capacitance of each chip in the figure is indispensable, and the wiring to the VDD and GND pins of the chips should be as short as possible, in order to achieve optimal decoupling effect and stable chip operation.

The first point controller only needs to be connected to the DIN port, and the FDIN port is grounded; in addition, if the breakpoint resume function is not required, all FDINs can be left floating. In addition, in order to reduce the thermal power consumption of the IC, a 33R resistor can be connected to the VDD port.

Packaging diagram (SOP 8)



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min | Max | Min | Max |
| A | 1.350 | 1.750 | 0.053 | 0.069 |
| A1 | 0.100 | 0.250 | 0.004 | 0.010 |
| A2 | 1.350 | 1.550 | 0.053 | 0.061 |
| b | 0.330 | 0.510 | 0.013 | 0.020 |
| c | 0.170 | 0.250 | 0.006 | 0.010 |
| D | 4.700 | 5.100 | 0.185 | 0.200 |
| E | 3.800 | 4.000 | 0.150 | 0.157 |
| E1 | 5.800 | 6.200 | 0.228 | 0.244 |
| e | 1.270(BSC) | | 0.050(BSC) | |
| L | 0.400 | 1.270 | 0.016 | 0.050 |
| θ | 0° | 8° | 0° | 8° |

(All specs and applications shown above subject to change without prior notice.)